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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Patricia B. Smith, et al.

Docket Number: TI-29811

Serial No.: 09/975,639

Art Unit: 2818

Filed: 10/11/01

Examiner: Quoc Dinh Hoang

For: Hydrogen Plasma Photoresist Strip and Polymeric Residue
Cleanup Process for Low Dielectric Constant Materials

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NAME OF INVENTOR(S): Patricia B. Smith, et al.	
TITLE OF INVENTION: Hydrogen Plasma Photoresist Strip and Polymeric Residue Cleanup Process for Low Dielectric Constant Materials	
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